Blockchain for IoT-Based Smart Cities: Advances, Requirements, and Future Challenges

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Message from the Guest Editors

Blockchain technology in smart cities can serve as a platform for exchanging data with a high degree of reliability and transparency without the need for a centralized entity. In recent years, there has been a notable increase in interest in IoT-based smart cities from both academia and industries. In this Special Issue, we aim to highlight the role of blockchain technology in various aspects, including smart transportation, smart healthcare, information security, infrastructure security, various facilities, communication networks, cloud computing, supply chain protection, distributed computing, scalability of blockchain, blockchain-backed IoT-based election systems, data storage, etc. We encourage researchers from various domains to foster collaboration among such interdisciplinary areas and to deliver their contributions on various topics related to blockchain for IoT-based smart cities. This Special Issue covers recent advancements in blockchain for IoT-based smart cities. It will also cover the requirements of blockchain and future challenges.

Special Issue

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Message from the Editor-in-Chief

I would like to introduce the new, online, and open access journal *Telecom*. The purpose of *Telecom* is to publish high-quality research papers as well as review articles that address recent advances in communications technology. We invite researchers to contribute original papers describing applications and experiences in emerging trends of all fields of telecommunications engineering. *Telecom* also welcomes Special Issue proposals from academics and industrial researchers. We aim to facilitate more collaboration between scientists and engineers around the world, such that they will produce their innovative ideas and submit their cutting-edge technologies to *Telecom*. We anticipate the receipt of your contributions to *Telecom*, and we welcome your comments and ideas on how to improve this journal.

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